PCB Number: PMP15027
PCB Rev: E3

PCB
LOGO
Pb-Free Symbol

Assembly Note
This Assembly Note is for PCB labels only

Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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